

Electronic Patent Application Fee Transmittal

Application Number:	10552441
Filing Date:	07-Oct-2005
Title of Invention:	EPOXY RESIN MOLDING MATERIAL FOR SEALING USE AND SEMICONDUCTOR DEVICE
First Named Inventor/Applicant Name:	Ryoichi Ikezawa
Filer:	William Ivan Solomon/Ricardo Perez
Attorney Docket Number:	1204.45467X00

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	4	3	12
Total in USD (\$)				1752